

MA3Z080D, MA3Z080E (MA80WA, MA80WK)

Silicon epitaxial planar type

For band switching

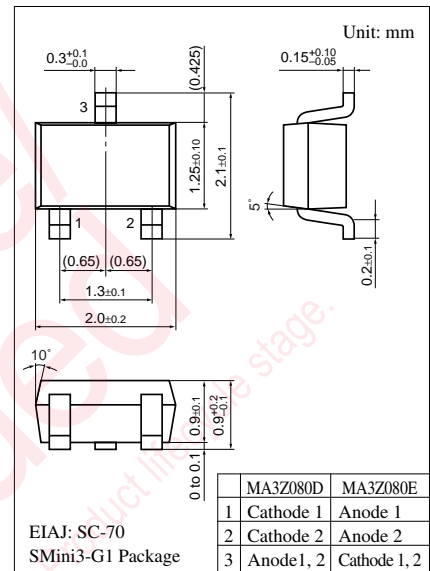
■ Features

- Low forward dynamic resistance r_f
- Less voltage dependence of diode capacity C_D
- S-Mini type package, allowing downsizing of equipment and automatic insertion through the taping package

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage (DC)	V_R	35	V
Forward current (DC)	I_F	100	mA
Operating ambient temperature *	T_{opr}	-25 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

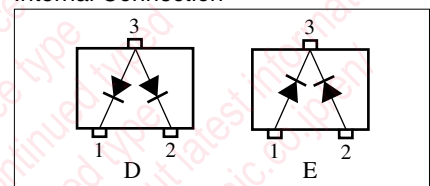
Note) *: Maximum ambient temperature during operation



Marking Symbol

- MA3Z080D: M1X
- MA3Z080E: M1Y

Internal Connection



■ Electrical Characteristics $T_a = 25^\circ\text{C}$

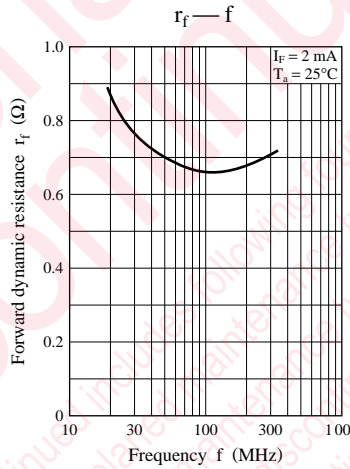
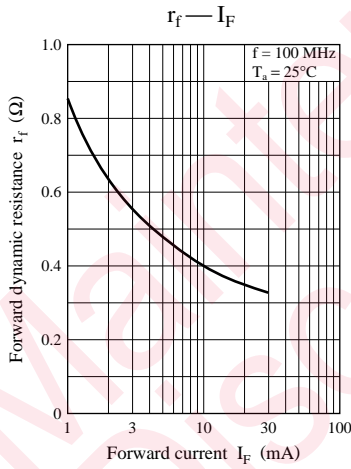
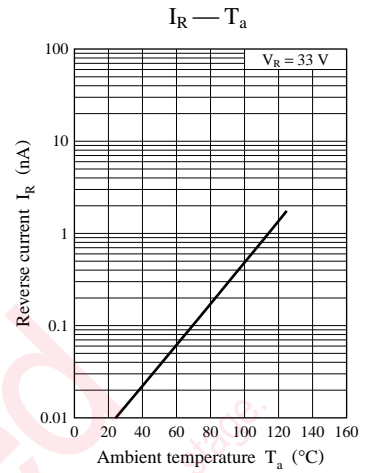
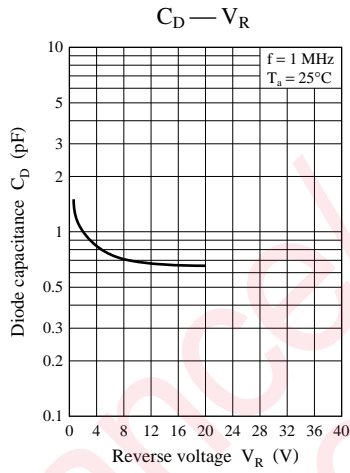
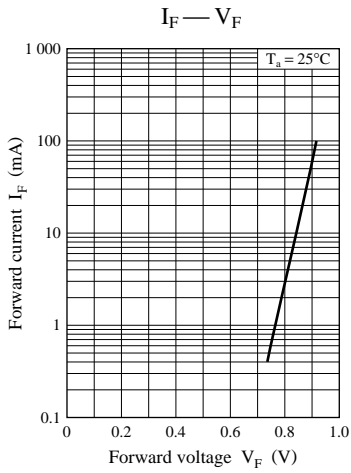
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse current (DC)	I_R	$V_R = 33\text{ V}$		0.01	100	nA
Forward voltage (DC)	V_F	$I_F = 100\text{ mA}$		0.92	1.0	V
Diode capacitance	C_D	$V_R = 6\text{ V}, f = 1\text{ MHz}$		0.9	1.2	pF
Forward dynamic resistance *	r_f	$I_F = 2\text{ mA}, f = 100\text{ MHz}$		0.65	0.85	Ω

Note) 1. Each characteristic is a standard for individual diode

2. Rated input/output frequency: 100 MHz

3. *: Measuring instrument; YHP MODEL 4191A RF IMPEDANCE ANALYZER

Note) The part number in the parenthesis shows conventional part number.



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